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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM 10099861	FILING DATE 03/15/2002	CLASS 420	SUBCLASS 6	GAU 1742	EXAMINER J. M. ...
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**APPLICANTS: Yeh Shing; Carter Bradley; Melcher Curtis;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials		ATTORNEY DOCKET NO DP-305031
TITLE : Lead-free solder alloy and solder reflow process		

U.S. DEPT. OF COMM./PAT. & TM.-PTO-435L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE Amount Due Date Paid		DRAWING	
		Sheets Drwg.	Figs. Drwg. Print Fig.
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner PREPARED FOR ISSUE Application Examiner	
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